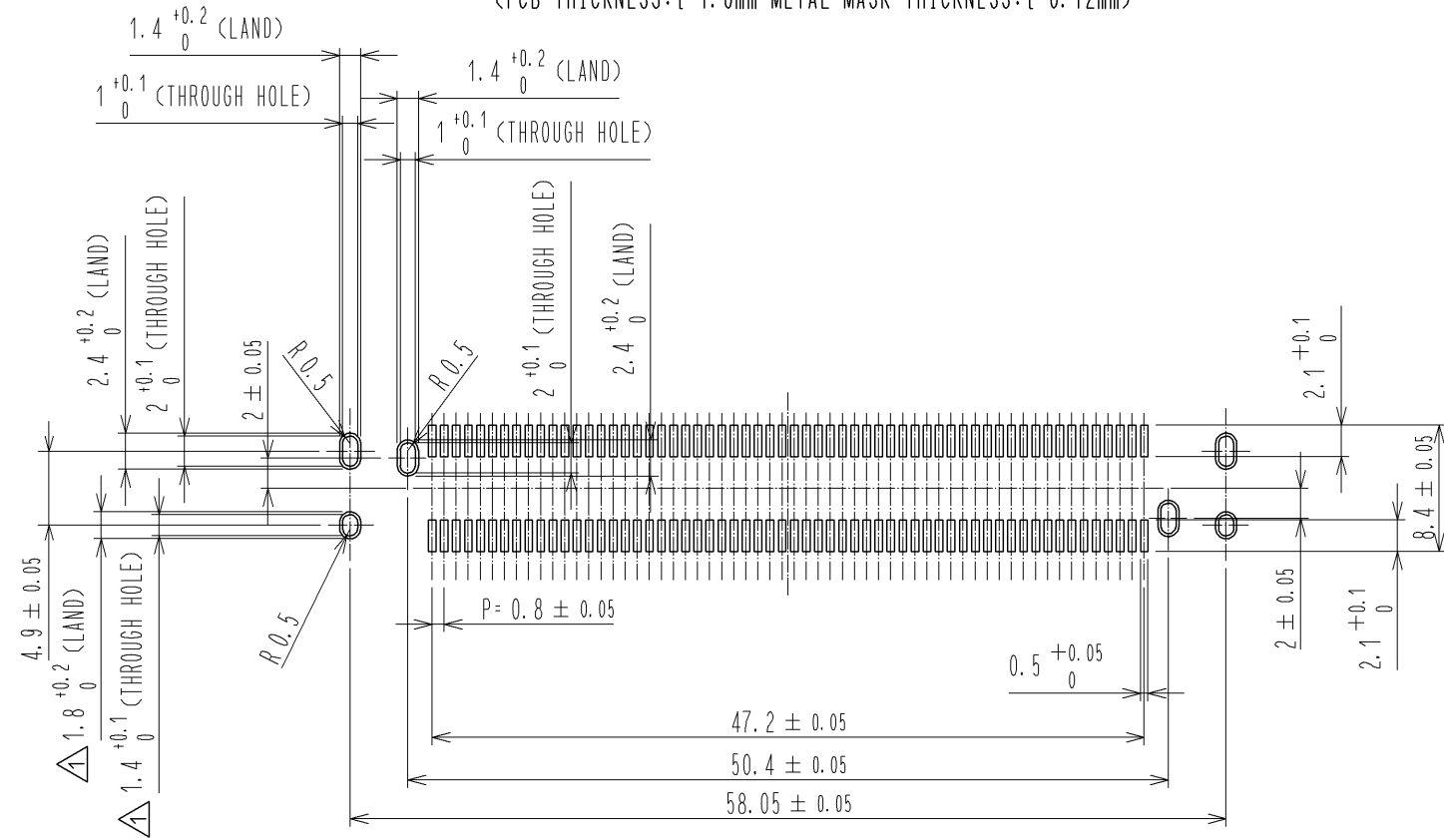


- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 - ③ MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 - ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2) REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 - ⑤ THIS IS PACKAGED IN TRAY. (40pcs/TRAY)
 - ⑥ BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 - ⑦ THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	7	POLYIMIDE	
2	POLYAMIDE	BLACK UL94V-0	6	POLYSTYRENE	
1	POLYAMIDE	BLACK UL94V-0	5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
NO.	MATERIAL	FINISH . REMARKS	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm

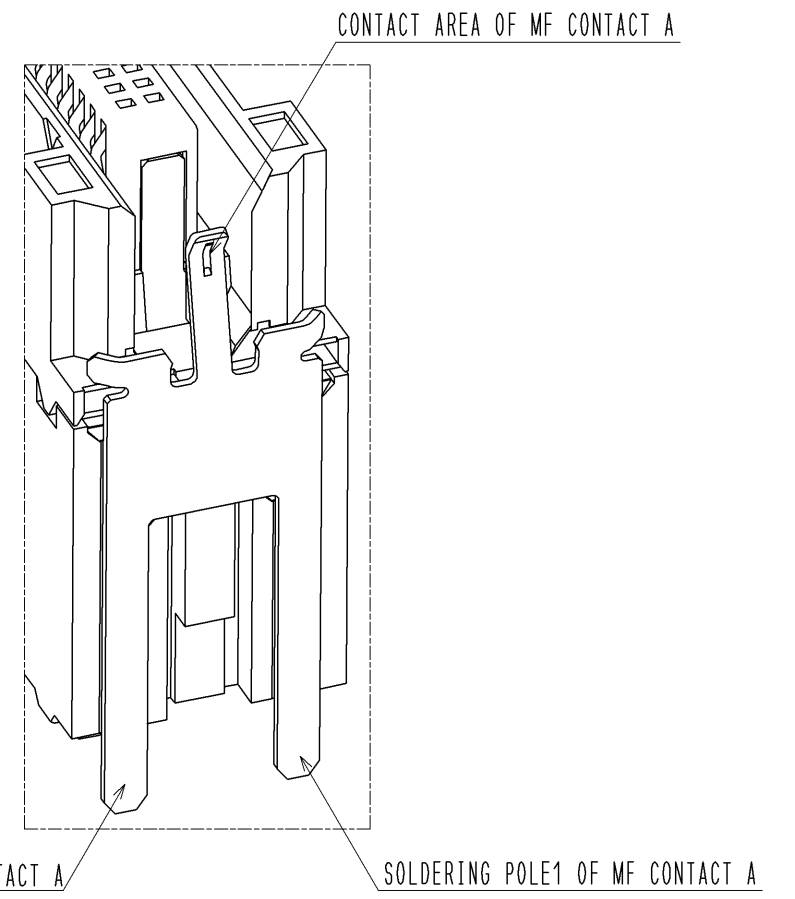
UNITS	mm	SCALE	2 : 1	COUNT	4	DESCRIPTION OF REVISIONS	DESIGNED	TH. SANO	CHECKED	KI. HIROKAWA	DATE	11.07.21
APPROVED : HS. OKAWA		11.03.17		DRAWING NO.		EDC3-334393-00						
CHECKED : KI. HIROKAWA		11.03.17		PART NO.		FX18-120S-0.8SV20						
DESIGNED : TH. SANO		11.03.17		CODE NO.		CL579-0033-9-00						
DRAWN : TH. SANO		11.03.17										

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

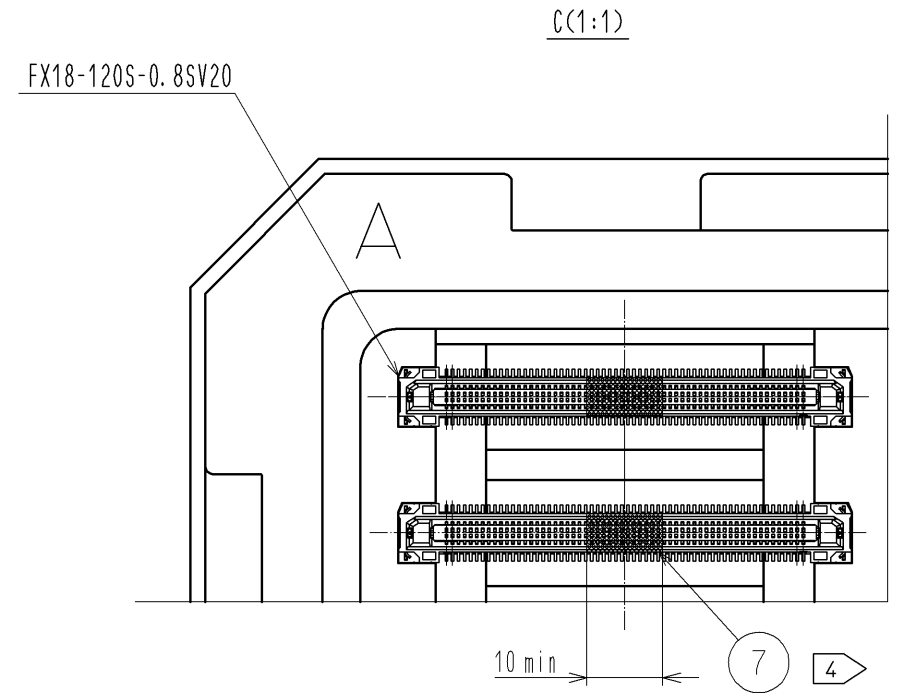
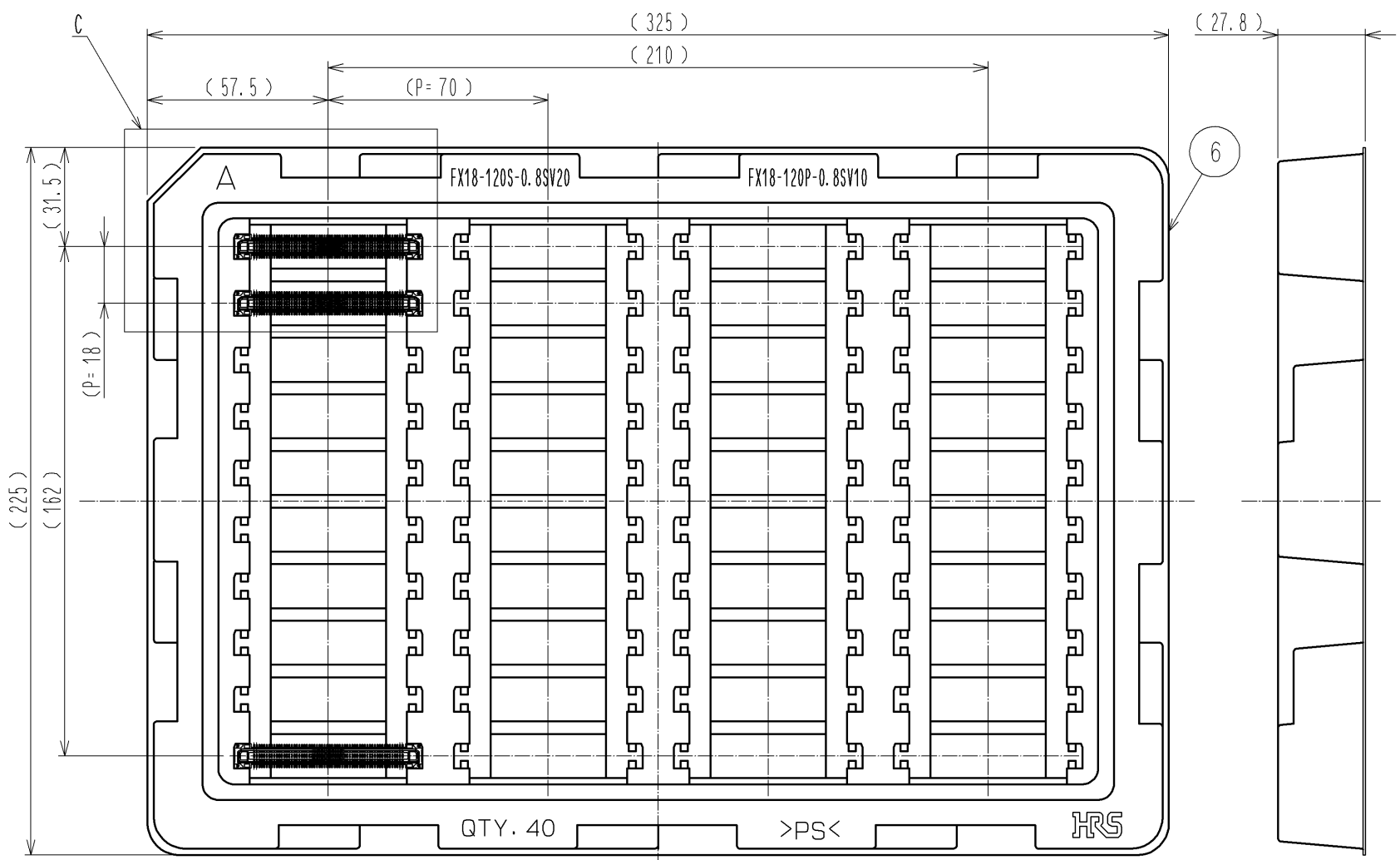


5 DRAWING FOR PACKING(1:2)

1 B CONFIGURATION OF MF CONTACT A



NOTE B SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS	DRAWING NO.	EDC3-334393-00	1/2
	PART NO.	FX18-120S-0.8SV20	
	CODE NO.	CL579-0033-9-00	